

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

MAIL STOP PATENT APPLICATION

Commissioner of Patents

P.O. Box 1450

Alexandria, VA 22313-1450

17958 U.S. PRO
10/645675
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Re: Inventor(s): Lihua Li, Tsutomu Tanaka, Tzu-Fang Huang, Li-Qun Xia, Dian Sugiarto, Visweswaren Sivaramakrishnan, Peter Wai-Man Lee and Mario David Silvetti.
 Title: METHODS OF REDUCING PLASMA-INDUCED DAMAGE FOR ADVANCED PLASMA CVD DIELECTRICS

Transmitted herewith is the patent application identified above, including:

Specification, claims and abstract, totaling 25 pages.
 Drawings totaling 8 pages, Formal Informal.
 Executed Declaration and Power of Attorney.
 Information Disclosure Statement w/ Form 1449 and References.
 Assignment of the invention to **Applied Materials, Inc.**
 Assignment Recordation Cover Sheet

FEE CALCULATION

	NUMBER OF CLAIMS FILED	LESS NUMBER PAID BY BASIC FEE	NUMBER OF EXTRA CLAIMS (Not less than zero)	LARGE ENTITY FEE
Basic Fee				\$ 750.00
Total Claims	31	- 20 = 11	X \$ 18 =	198.00
Independent Claims	5	- 3 = 2	X \$ 84 =	168.00
First Presentation of Multiple Dependent Claims		+250		-0-
Total Filing Fee Calculation				\$1116.00

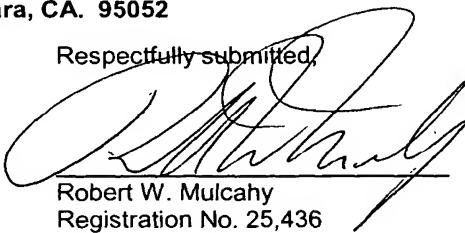
The Commissioner is hereby authorized to charge \$1116.00 to Deposit Account No. 50-1074/8338/DSM/LOW KJW.
 The Commissioner is hereby authorized to charge any additional fees which may be required, or credit any overpayment to Deposit Account No. 50-1074/8338/DSM/LOW KJW. A duplicate copy of this transmittal is enclosed.
 Please address all future correspondence to:

PATENT COUNSEL
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 Legal Affairs Department
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I hereby certify that this correspondence is being deposited with the United States Postal Service as express mail in an envelope addressed to: Mail Stop Patent Application, Commissioner of Patents and Trademarks, P.O. Box 1450, Alexandria, VA. 22313-1450

Express Mail Receipt No.: EV335470113USDate of Deposit: AUGUST 20, 2003Signature: Emmakor

Respectfully submitted,


 Robert W. Mulcahy
 Registration No. 25,436